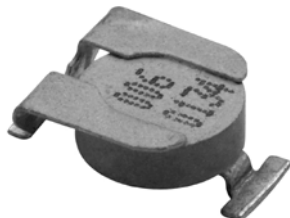


SMD PTC Thermistors For Overload Protection


RoHS
COMPLIANT

FEATURES

- Ideal for pick-and-place circuit assembly
- Low mounting height
- Suitable for reflow soldering
- Small ceramic diameter for faster response
- Low heat transfer to substrate
- Flat terminations for stable positioning and good solderability
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC

APPLICATIONS

Over-temperature/over-load protection:

- Telecom
 - Central office switching (C.O.)
 - Subscriber terminal equipment (T.E.)
 - Set top box
 - Modems
 - Cable TV communications
- General industry and automotive
 - Low power supplies overload protection
 - Data bus protection

DESCRIPTION

The component consists of a high-performance PTC ceramic disc mounted in a lead-frame for direct soldering onto a printed-circuit board (PCB) or substrate.

The ceramic is soldered to the leadframe by a local reflow process, during which the solder layer is melted to the metallized ceramic surface using a low residue flux.

MARKING

- All SMD PTCs are marked with the last 3-digits of the type number (XXX) and a date code (YYWW)

QUICK REFERENCE DATA		
DESCRIPTION	VALUE	
	STANDARD TYPES (1) (2)	TELECOM TYPES (1) (2)
Nominal R25	2 Ω to 500 Ω	10 Ω to 70 Ω
Resistance tolerance	± 10 %; ± 15 %; ± 20 %	
Maximum overload current (voltage dependent)	2 A to 10 A	
Non-trip current	50 mA to 500 mA at 25 °C	50 mA to 100 mA at 70 °C
Maximum voltage	16 V _{RMS} to 400 V _{RMS}	220 V _{RMS} to 600 V _{RMS}
Response time at 25 °C and 20 W overload power	< 1 s	
Matching	-	Down to 0.5 Ω
Maximum continuous power at 25 °C	2 W	

Notes

- (1) Customized products are available on request
 (2) Coated and/or reinforced types are available on request

ELECTRICAL DATA AND ORDERING INFORMATION

RESISTANCE		MATCHING Ω	V MAX. (V)	I _{nt} at		I _t at	MAX. TRIP-TIME at 1 A (s)	I _{max.} at V _{max.} (A)	CATALOG NUMBER		
R ₂₅ (Ω)	TOL (%)			25 °C (mA)	70 °C (mA)	25 °C (mA)			12NC	SAP CODING	
Telecommunication Types											
10	20	no	245	165	100	270	3.0	2.0	2381 661 97012 ⁽³⁾	PTCTZ3NR100GTE ⁽³⁾	
10	20	0.5	245	165	100	270	3.0	2.0	2381 661 97016 ⁽³⁾	PTCTZ3MR100GTE ⁽³⁾	
40	25	no	265	80	50	130	0.8	2.0	2381 661 97002	PTCTZ3NR400HTE	
25	20	1	265	120	70	220	1.3	2.0	2381 661 97005 ⁽³⁾	PTCTZ3MR250HTE ⁽³⁾	
15 to 20	-	no	300	150	100	250	1.5	1.5	2381 661 97004 ⁽³⁾	PTCTZ3NR150KTE ⁽³⁾	
15 to 20	-	0.5	300	150	100	250	1.5	2.0	2381 661 97003 ⁽³⁾	PTCTZ3MR150KTE ⁽³⁾	
20	20	0.5	300	120	70	250	1.4	1.5	2381 661 97018 ⁽³⁾	PTCTZ3MR200KTE ⁽³⁾	
35	+ 15/- 20	1	425	110	70	175	1.0	0.7	2381 661 97009 ⁽³⁾	PTCTZ3MR350MTE ⁽³⁾	
50	20	1	425	90	60	150	0.8	0.7	2381 661 97019	PTCTZ3MR500MTE	
General Industrial Types											
3.3	25	-	24	400	-	650	6.0	8.0	2381 661 97013 ⁽³⁾	PTCTZ3NR339CTE ⁽³⁾	
9.4	25	-	60	150	100	300	1.8	3.0	2381 661 97011 ⁽³⁾	PTCTZ3NR949ETE ⁽³⁾	

Note

- (3) These types pass ITU-K20-21-45 edition 2003 telecommunication protection recommendation

PTC OUTLINES

PTC SMD ceramic size: 6.5 mm


DIMENSIONS OF SOLDER LANDS in millimeters

DIMENSIONS in millimeters

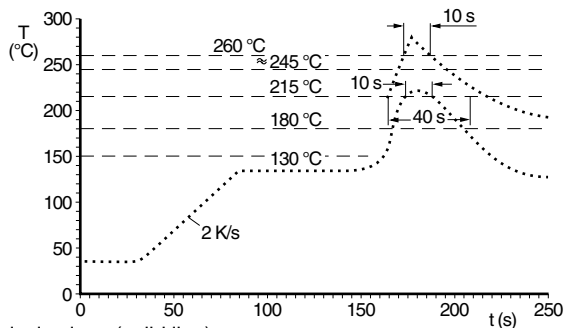
MATERIAL INFORMATION

REF.	DESCRIPTION	MATERIAL AND REMARKS
1	Ceramic	BaTiO ₃ doped
2	Metallization	NiCr Ag layer (vacuum deposition)
3	Leadframe	Ni plated phosphor bronze material covered by PbSn8 solder layer

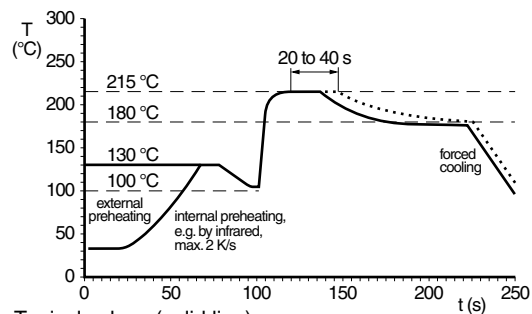
SOLDERING CONDITIONS

This SMD thermistor is only suitable for reflow soldering, in accordance with JEDEC J-STD-020D. Soldering processes which can be used are reflow (infrared and convection heating) and vapour phase. The maximum temperature of 260 °C during 10 s should not be exceeded and no liquid flux should be allowed to reach the ceramic body.

Typical examples of a soldering processes that will provide reliable joints without damage, are shown below.

Reflow soldering


Typical values (solid line)
Process limits (dotted lines)

Vapour phase soldering


Typical values (solid line)
Process limits (dotted lines)

HANDLING PRECAUTIONS

The special leadframe construction and the applied processes do not allow high handling forces on the component. Because of the nature of PTC ceramic material the component should not be touched with bare hands, as the residue of perspiration can influence component behaviour at high temperatures.

Handling forces vertically applied to the centre of the component should be limited to 5 N in the non-soldered condition and to 10 N in the soldered. These forces should not be exceeded during the handling, transportation and packaging of the soldered product.

For those applications where higher handling forces can be present, a reinforced version is available on request.



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